

Claims after this response:

1. A packaged die comprising:

a die pad having a die having an electrical circuit thereon attached thereto;

a plurality of leads arranged around said die pad, at least one of said leads being connected to said die;

a power ring comprising a conductor disposed between said leads and said die pad, at least one power connection on said die being connected to said power ring; and

a layer of encapsulating material covering said die, said die pad, said power ring, and said leads, said layer having a top surface, a bottom surface, and side surfaces, wherein each of said leads comprises a conductor having a portion thereof exposed on said bottom surface and wherein a portion of said conductor in said power ring is exposed on said bottom surface.

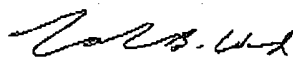
2(Withdrawn). The packaged die of Claim 1 wherein said exposed portions of said conductors further comprise solder balls.

3. The packaged die of Claim 1 wherein said die pad, said leads, and said power ring each extend to at least one of said side surfaces.

4(Withdrawn). The packaged die of Claim 1 wherein each of said leads comprises a conductor having a portion thereof that is not exposed on said bottom surface and wherein a portion of said conductor in said power ring is not exposed on said bottom surface.

I hereby certify that this paper is being sent by FAX to 703-872-9306.

Respectfully Submitted,



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